

Application:

- Intel Nehalem Socket 1366 2U
- Xeon (45nm) W5500/X5500/E5500/L5500 CPU sequence

Pictures



Thermal & Mechanical Spec.:

- Thermal performance for 130W CPU
- HSK Assembly Weight: 590 g (ref.)
- Clipping Force: 16 Kg (ref.)

Component Specification:

1. Heat Sink

Type: Cu/Al Fins + Cu Base + 4x Heatpipes
Material: A1100/ADC12/C1100 or Equivalent.
Dimension: 90*90*64 mm

2. Thermal interface material

Material: Dow Corning TC-1996 or Equivalent.

3. Fan

(60x60x25 mm with PWM Control)

Rated Voltage: 12 V

Life Time:

Two ball bearing 80000 hrs

Connector:

a. Lead wire: UL 1061 AWG#26

pin 1: black wire-----(-)

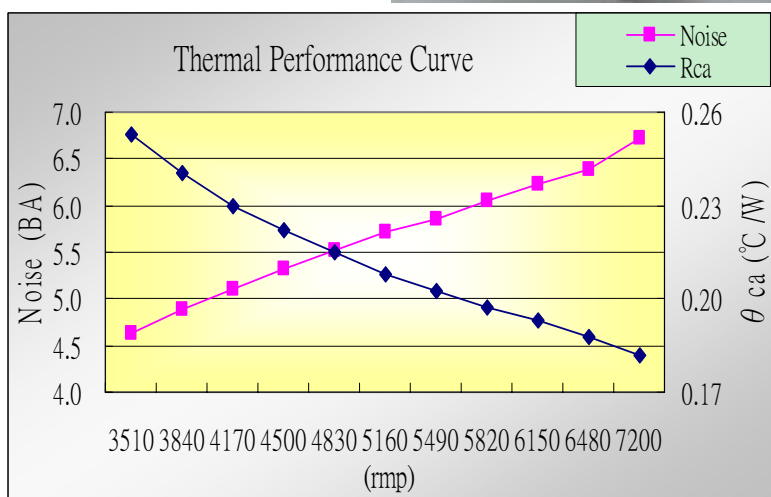
pin 2: yellow wire-----(+)

pin 3: green wire----- (F00)

pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent



* All readings are typical values at rated voltage.



* Specifications are subject to change without notice

Application:

- Intel Nehalem Socket 1366 2U
- Xeon (45nm) E5500/L5500 CPU sequence

Pictures



Thermal & Mechanical Spec.:

- Thermal performance for 80W CPU
- HSK Assembly Weight: 500 g (ref.)
- Clipping Force: 16 Kg (ref.)

Component Specification:

1. Heat Sink
Type: Extrude HSK
Material: Aluminum A6063 or Equivalent.
Dimension: 90*90*64 mm
2. Thermal interface material
Material: Dow Corning TC-1996 or Equivalent.
3. Fan

(60x60x25 mm with PWM Control)

Rated Voltage: 12 V

Life Time:

Two ball bearing 80000 hrs

Connector:

- a. Lead wire: UL 1061 AWG#26

pin 1: black wire-----(-)

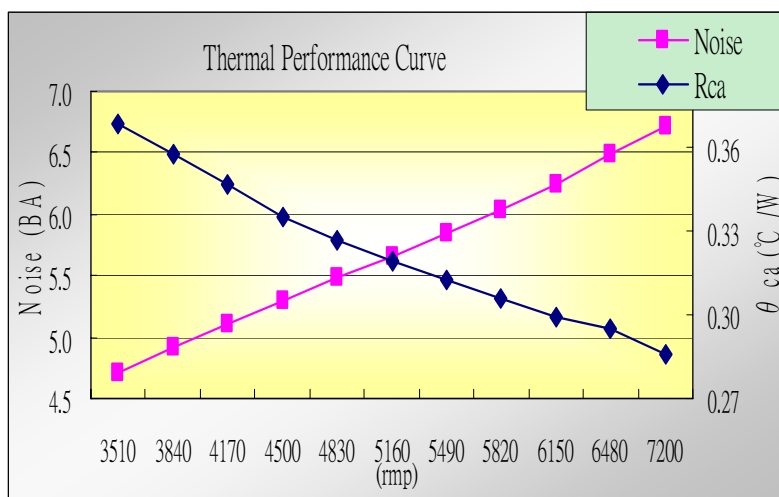
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- b. Housing: Molex 47054-1000 or equivalent

- c. Terminal: Molex 2759T 08-50-0113 or equivalent



* All readings are typical values at rated voltage.



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